DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

the specifica	tion of which			
(Check one)	Application Se	n rial No		
I hereby stat specification	e that I have rev including the cl	iewed and under aims,as amende	estand the contents of the deby any amendment	of the above-idenified nt referred to above.
I acknowledg this applicat	e the duty to disc ion in accordance	close information e with Title 37,	n which is material t Code of Federal Reg	to the examination of gulations, 1.56.
foreign applidentified bel	ication(s) for pat low any foreign ap	tent or inventor plication for pat	's certificate listed	tates Code,119 of any below and have also tificate having a filing :
Prior Foreig	n Application(s)			Priority Claimed
	Number)	(Country)	(Day/Month/Year filed)	-

I hereby claim the benefit under Title 35, United States Code, 120 of any United States application(s) listed below and, in so far as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code 112. I acknowledge the duty to

disclose material information as defined in Title 37, Code of Federal Regulations, 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No)	(Filing Date)	(Patented,Pending,Abandoned)
(Application Serial No)	(Filing Date)	(Patented, Pending, Abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor MIKIO FUJITA					
			→Date_MARCH 21, 2001.		
nesidence_					
Post Office	Address	146-0092	JAPAN.		
Full name of sec	cond inventor				
→Inventor's	signature_		→Date		
Residence_					
Post Office	Address				